

Title (en)

Adhesive composition and insulating substrate clad with this composition used for producing printed-circuit boards.

Title (de)

Klebende Zusammensetzung und mit dieser Zusammensetzung bekleideter isolierender Träger unter Verwendung von gedruckten Schaltungsplatten.

Title (fr)

Composition adhésive et substrat isolant revêtu de cette composition utilisé pour la fabrication de plaquettes de circuits imprimés.

Publication

EP 0192365 A2 19860827 (EN)

Application

EP 86300640 A 19860130

Priority

JP 1962485 A 19850204

Abstract (en)

An insulating substrate having on at least one surface a layer of an adhesive composition comprising (A) a modified phenolic resin and (B) acrylonitrile-butadiene rubber is suitable for producing, by an additive process, printed circuit boards having excellent solder heat resistance.

IPC 1-7

C08L 61/06; **C08L 61/34**; **C09J 3/16**; **C23C 18/20**; **H05K 3/38**

IPC 8 full level

C08G 8/24 (2006.01); **C08L 7/00** (2006.01); **C08L 9/02** (2006.01); **C08L 21/00** (2006.01); **C08L 33/00** (2006.01); **C08L 33/02** (2006.01); **C08L 61/00** (2006.01); **C08L 61/04** (2006.01); **C08L 61/06** (2006.01); **C08L 61/10** (2006.01); **C09J 109/02** (2006.01); **C09J 121/00** (2006.01); **C09J 161/00** (2006.01); **C09J 161/06** (2006.01); **C09J 161/34** (2006.01); **H05K 3/38** (2006.01); **H05K 3/18** (2006.01)

CPC (source: EP KR US)

C08G 8/24 (2013.01 - EP US); **C09J 109/02** (2013.01 - EP KR US); **C09J 161/06** (2013.01 - EP US); **C09J 161/34** (2013.01 - EP US); **H05K 3/387** (2013.01 - EP US); **C08L 9/02** (2013.01 - EP US); **C08L 2666/08** (2013.01 - EP US); **C08L 2666/16** (2013.01 - EP US); **H05K 3/181** (2013.01 - EP US); **H05K 2201/0133** (2013.01 - EP US); **Y10S 428/901** (2013.01 - EP US); **Y10T 29/49124** (2015.01 - EP US); **Y10T 428/259** (2015.01 - EP US); **Y10T 428/31511** (2015.04 - EP US); **Y10T 428/31688** (2015.04 - EP US); **Y10T 428/31877** (2015.04 - EP US); **Y10T 428/31935** (2015.04 - EP US); **Y10T 428/31942** (2015.04 - EP US)

Cited by

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